

## **PROCESS FOR FABRICATING A STRUCTURE COMPRISING AT LEAST TWO CHIPS ON A SUBSTRATE**

### **ABSTRACT**

The invention relates to a process for manufacturing a structure comprising at least two chips (p11, p12, p13, p14) on a receiver substrate (3), comprising:

- forming a pseudo-donor substrate (10) by placing at least one tile (P1, P2, P3) of at least one donor substrate (2) on a support substrate (1);
- bonding said pseudo-donor substrate (10) to a receiver substrate (3) via the tiles so that each tile at least partially covers at least two different zones of interest (Z1, Z2, Zn) of the receiver substrate (3);
- transferring a portion (P'1, P'2, P'3) of said tiles (P1, P2, P3) to the receiver substrate (3);
- at least one step of chemical-mechanical polishing of the tiles (P1, P2, P3) of the pseudo-donor substrate and/or of the tile portions transferred to the receiver substrate;
- after said at least one step of chemical-mechanical polishing, a removal of material from said tile portions (P'1, P'2, P'3) so as to divide each tile portion into at least two chips (p11, p12, p13, p14) each arranged on a respective zone of interest (Z1, Z2, Zn).

[ Figure 6 ]